

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A component mounting circuit board comprising:

a circuit pattern including a plurality of electrically conductive plates;

an inner electrical component electrically connected to the circuit pattern; [[and]]

a resin molded section made of a resin by way of molding so as to cover the circuit pattern and the inner electrical component, the resin molded section having an opening allowing an outer electrical component located outside the resin molded section to be connected to the circuit pattern therethrough;[[.]] and

a metal member embedded in the resin molded section so as to be located to correspond to a portion of the inner electrical component and electrically insulated from the circuit pattern, the metal member being provided with an exposed portion exposed outside the resin molded section.

2. (Currently Amended) [[The]] A component mounting circuit board comprising:

a circuit pattern including a plurality of electrically conductive plates;

an inner electrical component electrically connected to the circuit pattern;

a resin molded section made of a resin by way of molding so as to cover the circuit pattern and the inner electrical component, the resin molded section having an opening allowing an outer electrical component located outside the resin molded section to be connected to the circuit pattern therethrough; and

a metal member embedded in the resin molded section so as to be located at a portion corresponding to the inner electrical component, the metal member being discrete from the circuit pattern.

~~according to claim 1, wherein the resin molded section is made of an epoxy resin.~~

3. (Currently Amended) The component mounting circuit board according to claim 1, wherein the resin molded section is made of an epoxy resin. ~~a portion of the circuit pattern corresponding to the inner electrical component has member coupled thereto, the member and the portion being thicker than the remaining circuit pattern.~~

4. (Currently Amended) The component mounting circuit board according to claim ~~[[1]]~~ 2, wherein the resin molded section is made of an epoxy resin. ~~circuit pattern corresponding to the inner electrical component has an exposed portion exposed to the outside the resin molded section.~~

5. (Currently Amended) The component mounting circuit board according to claim 1, wherein the circuit pattern includes a portion corresponding to the inner electrical component and provided with a thicker portion thicker than a remaining portion. ~~further comprising a metal member embedded in the resin molded 1, further comprising a metal member embedded in the resin molded section so as to be located to correspond to a portion of the inner electrical component and electrically insulated from the circuit pattern, the metal member being provided with an exposed portion exposed outside the resin molded section.~~

6. (Currently Amended) The component mounting circuit board according to claim ~~[[1]]~~ 2, wherein the circuit pattern includes a portion corresponding to the inner electrical component and provided with a thicker portion thicker than a remaining portion. ~~further comprising a metal member embedded in the resin molded section so as to be located at a portion corresponding to the inner electrical component, the metal member being discrete from the circuit pattern.~~

7. (Currently Amended) The component mounting circuit board according to claim 1, wherein the circuit pattern includes a portion corresponding to the inner electrical component

and provided with an exposed portion exposed outside the resin molded section. further comprising a support provided on the resin molded section to support the outer electrical component.

8. (Currently Amended) The component mounting circuit board according to claim [[1]] 2, wherein the circuit pattern includes a portion corresponding to the inner electrical component and provided with an exposed portion exposed outside the resin molded section. further comprising a terminal provided on the circuit pattern so as to project outside the resin molded section.

9. (Currently Amended) The component mounting circuit board according to claim 1, further comprising a support provided on the resin molded section to support the outer electrical component. wherein the inner electrical component is connected to the circuit pattern by wire bonding.

10. (Currently Amended) The component mounting circuit board according to claim [[1]] 2, further comprising a support provided on the resin molded section to support the outer electrical component. wherein the outer electrical component is soldered to a portion of the circuit pattern corresponding to the opening.

11. (Currently Amended) The component mounting circuit board according to claim 1, further comprising a terminal provided on the circuit pattern so as to project outside the resin molded section. A microwave oven comprising:

a magnetron; and

a component mounting circuit board including, at least, a power supply circuit for driving the magnetron, and a switching circuit mounted thereon;

~~the component mounting circuit board includes a circuit pattern including a plurality of electrically conductive plates;~~

~~an inner electrical component electrically connected to the circuit pattern; and~~

~~a resin molded section made of a resin by way of molding so as to cover the circuit pattern and the inner electrical component.~~

12. (Currently Amended) The component mounting circuit board according to claim [[11]] 1, wherein the inner electrical component is connected to the circuit pattern by wire bonding. ~~the resin molded section includes an opening used when an outer electrical component located outside the resin molded section is connected to the circuit pattern.~~

13. (Currently Amended) The component mounting circuit board according to claim 2, wherein the inner electrical component is connected to the circuit pattern by wire bonding. ~~A method of making a component mounting circuit board comprising the steps of:~~

~~electrically connecting an inner electrical component to a circuit pattern including a plurality of electrically conductive plates;~~

~~covering the circuit pattern and the inner electrical component with a resin, thereby forming a resin molded section having an opening; and~~

~~electrically connecting an outer electrical component located outside the resin molded section through the opening.~~

14. (New) The component mounting circuit board according to claim 1, wherein the outer electrical component is soldered to a portion of the circuit pattern corresponding to the opening.

15. (New) The component mounting circuit board according to claim 2, wherein the outer electrical component is soldered to a portion of the circuit pattern corresponding to the opening.